

The Right Equipment for Automating Your Fluid Dispensing Applications!

• Adhesives • SMT Solder Paste & Epoxy • RTV & Silicones • Solder Mask • Encapsulants & Potting Compounds
• Silver Epoxy • Bonding Fluid • Ink

Demonstration Worksheet Programming Elements

DOT
GOUTTE
PUNKT



POT

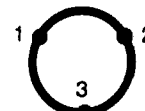


REPLISSAGE
FÜLLEN

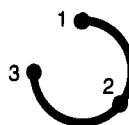
LINE
LIGNE
LINIE



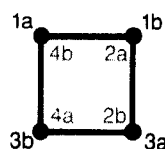
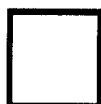
CIRCLE
CERCLE
KREIS



ARC
ARC
KREISBOGEN



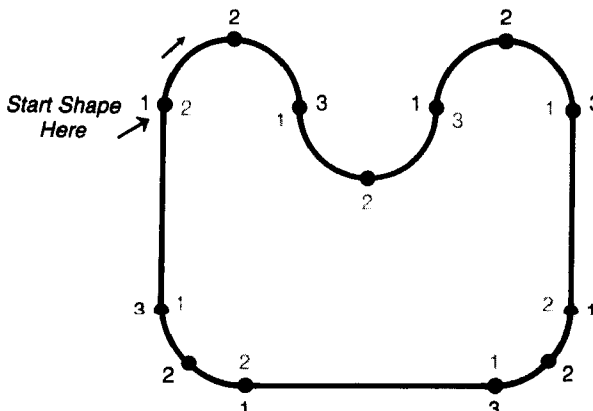
SQUARES
CARRÉS
QUADRAT



AREA PAINT
RECOUVREMENT
GEFÜLLTE FLÄCHEN



IRREGULAR SHAPES
FORMES IRRÉGULIÈRES
UNREGELMÄßIGE FORMEN



Line up to the lower left edge of the platen.
Aligner contre les butées du plateau.
Auf Plattenrand unten links ausrichten.

DOT SIZE

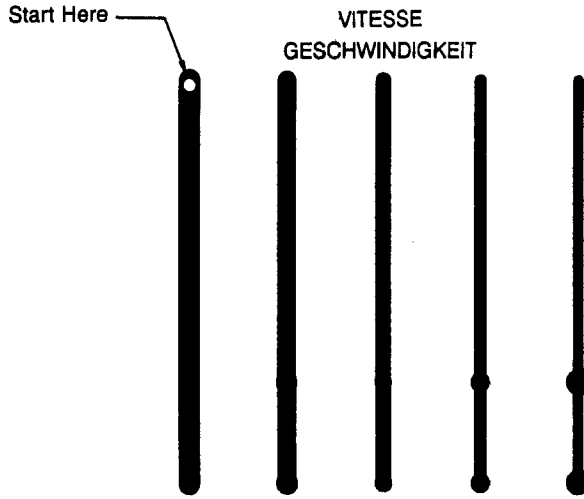


POTTING VOLUME



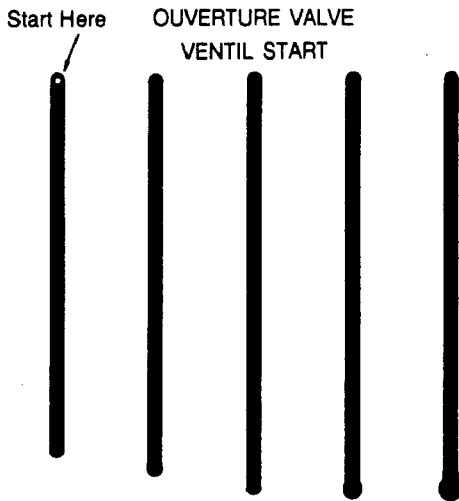
SPEED

VITESSE
GESCHWINDIGKEIT



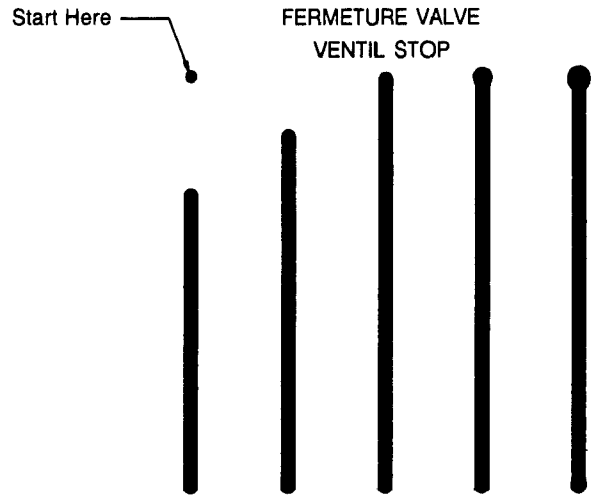
VALVE STARTUP

OUVERTURE VALVE
VENTIL START



VALVE SHUTOFF

FERMETURE VALVE
VENTIL STOP



NESTED REPEATS

